



SOT238-3

plastic leaded chip carrier; 52 leads; pedestal, 1.27 mm pitch,
19.1 mm x 19.1 mm x 4.38 mm body

11 October 2018

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	PLCC52
Package type industry code	PLCC52
Package style descriptive code	PLCC (plastic leaded chip carrier)
Package body material type	P (plastic)
IEC package outline code	112E11
JEDEC package outline code	MO-047
Mounting method type	S (surface mount)
Issue date	15-11-2001
Manufacturer package code	SOT238

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	19.05	19.125	19.2	mm
package width	19.05	19.125	19.2	mm
seated height	4.19	4.38	4.57	mm
nominal pitch	-	1.27	-	mm
actual quantity of termination	-	52	-	



2 Package outline

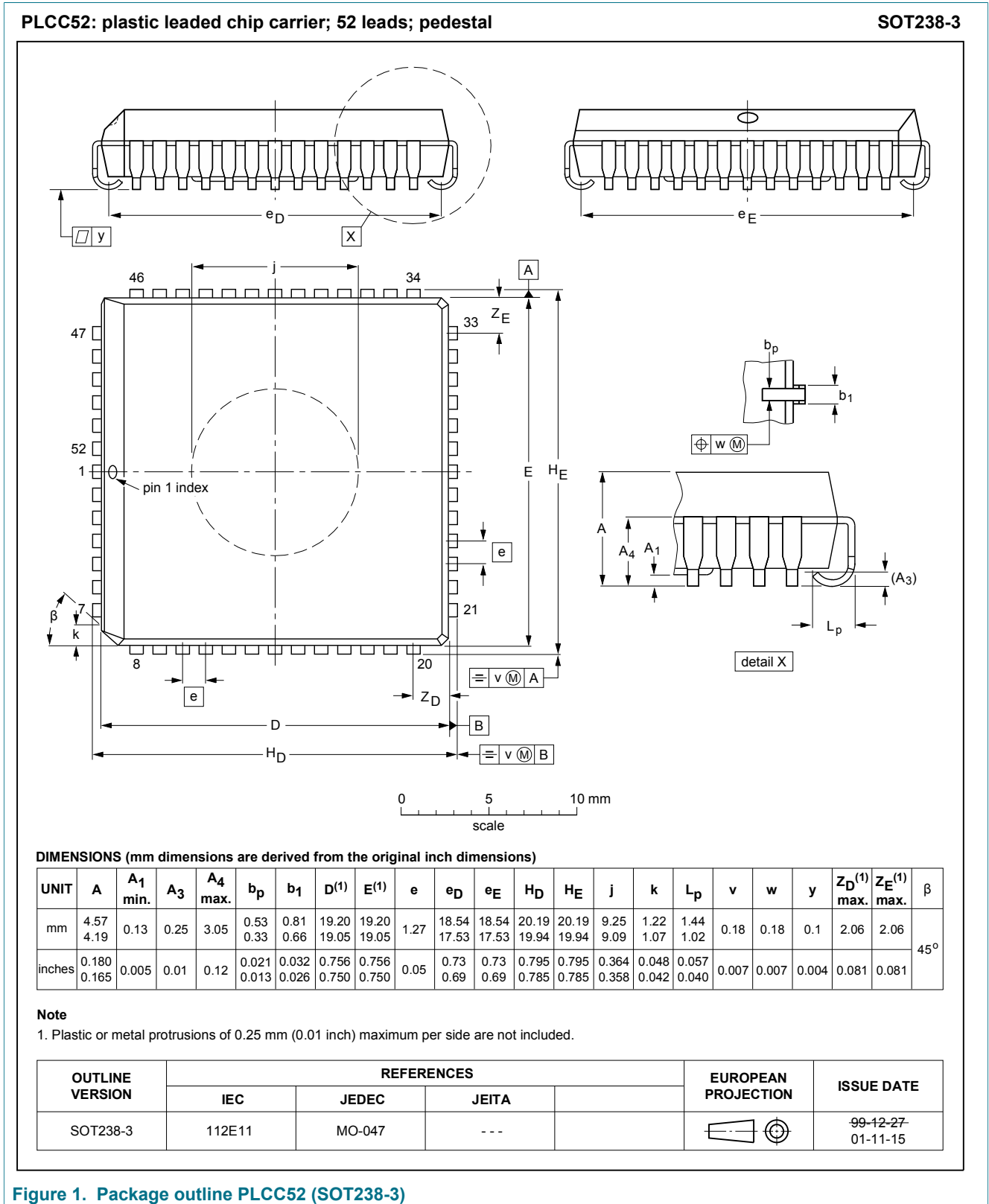
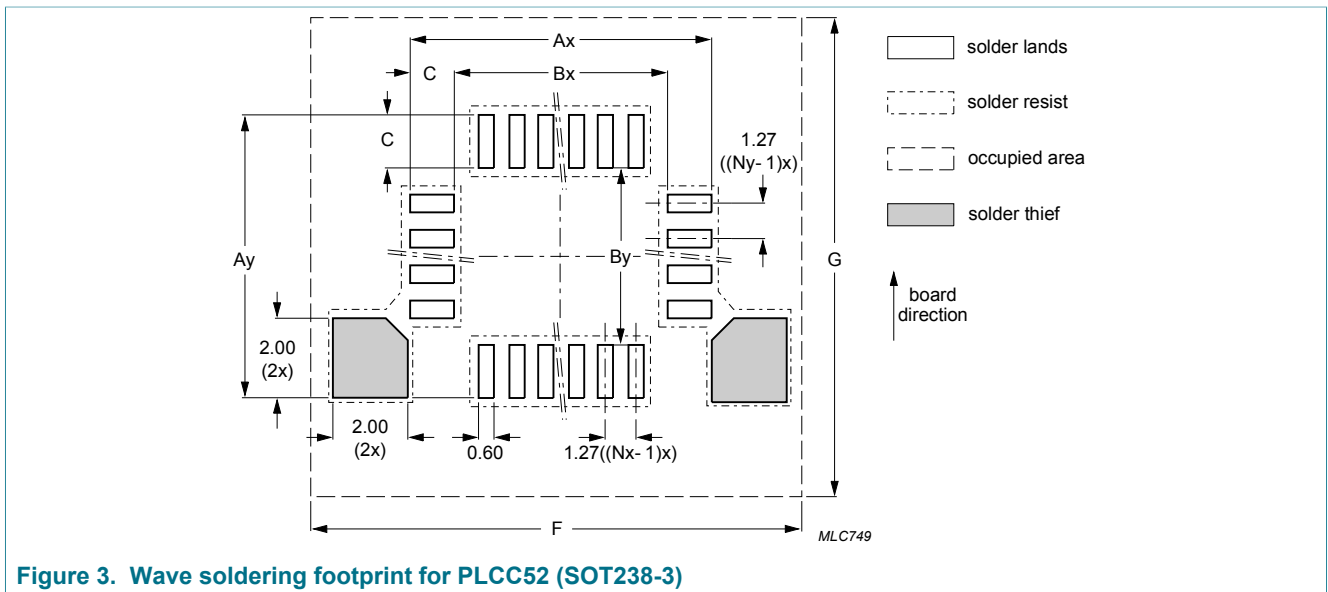
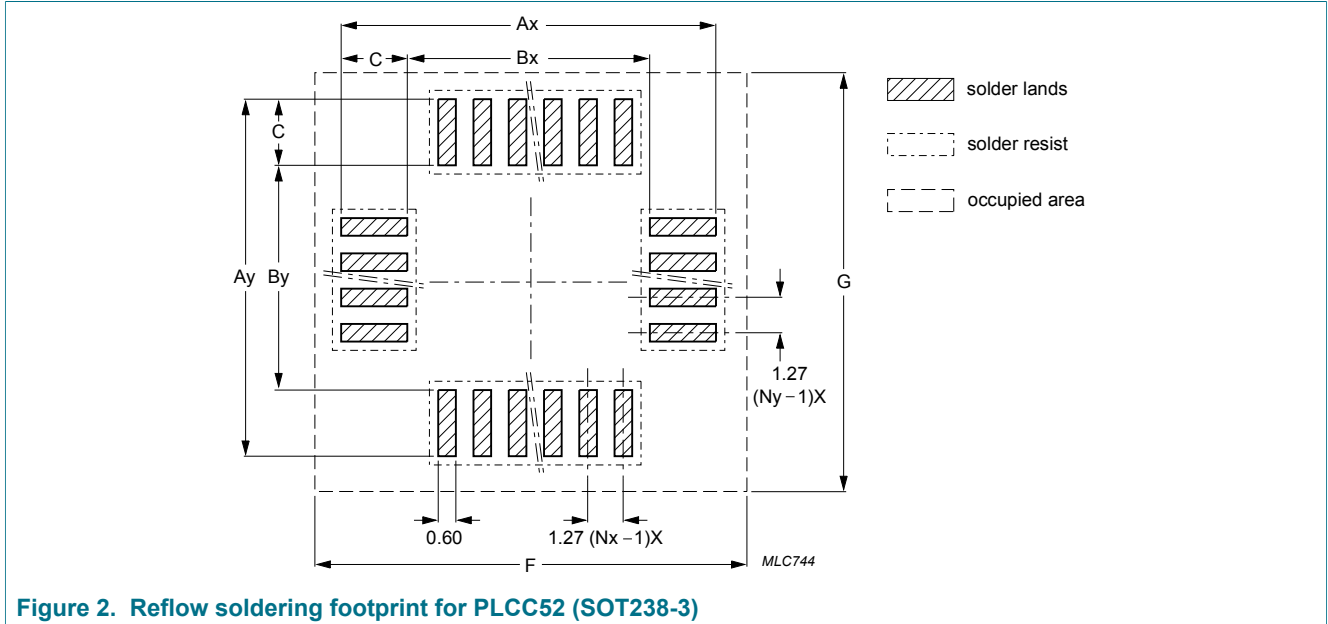


Figure 1. Package outline PLCC52 (SOT238-3)

3 Soldering



4 Legal information

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Contents

1 Package summary1
2 Package outline2
3 Soldering3
4 Legal information4